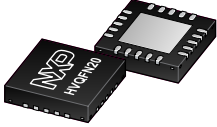


SOT917-7

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads;
20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

27 March 2024

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-02-2023
Manufacturer package code	98ASA02044D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	20	-	

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

2 Package outline

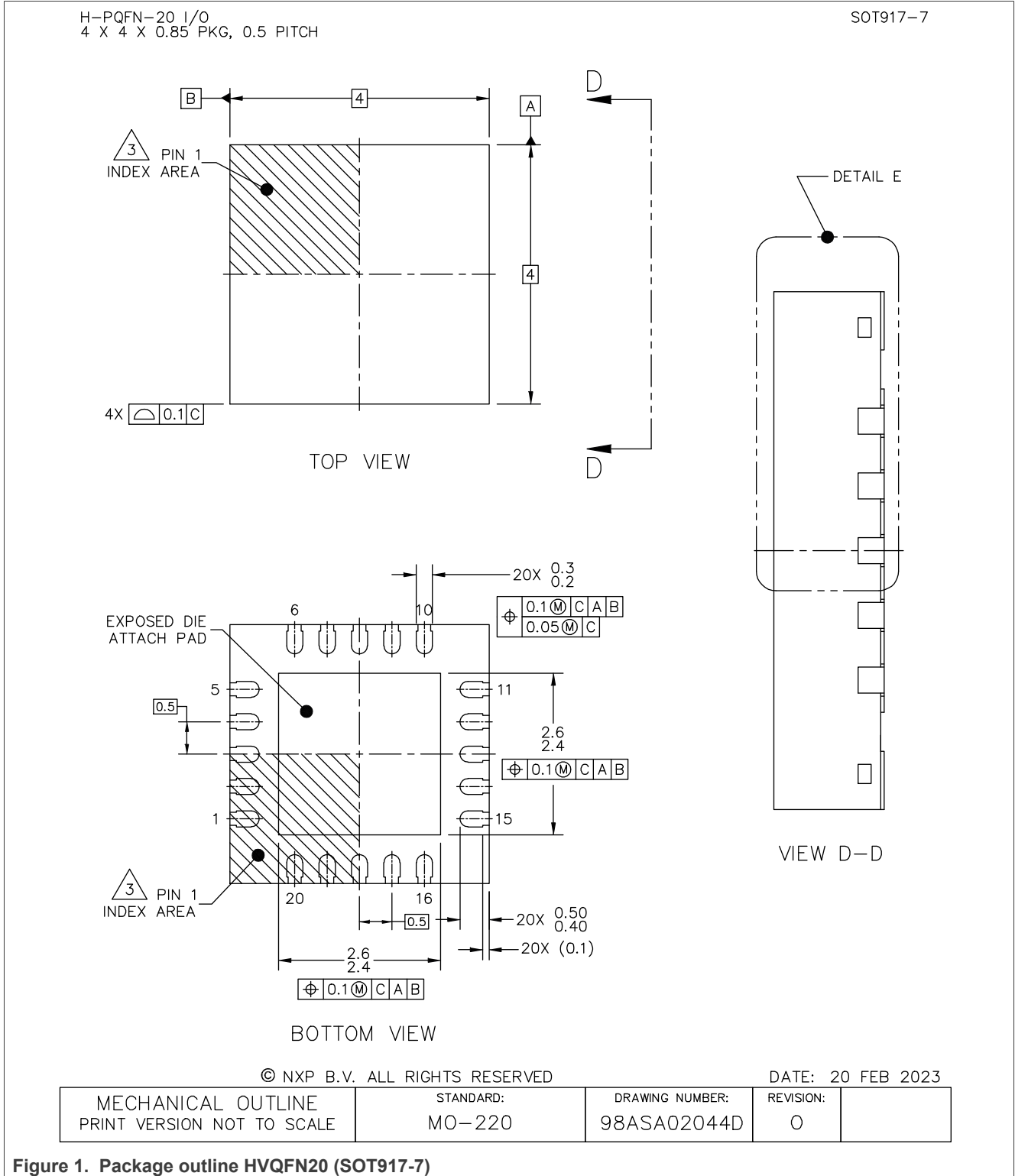
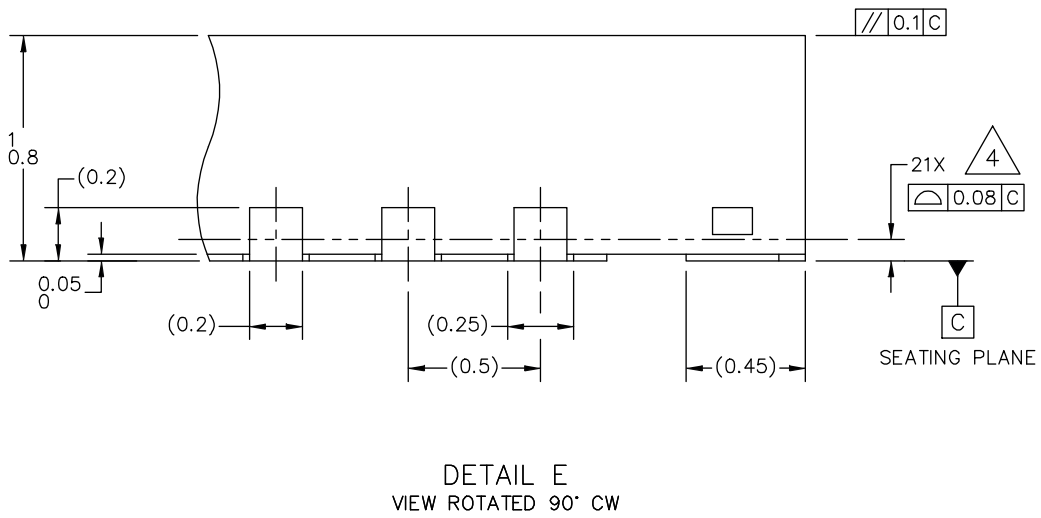


Figure 1. Package outline HVQFN20 (SOT917-7)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-7



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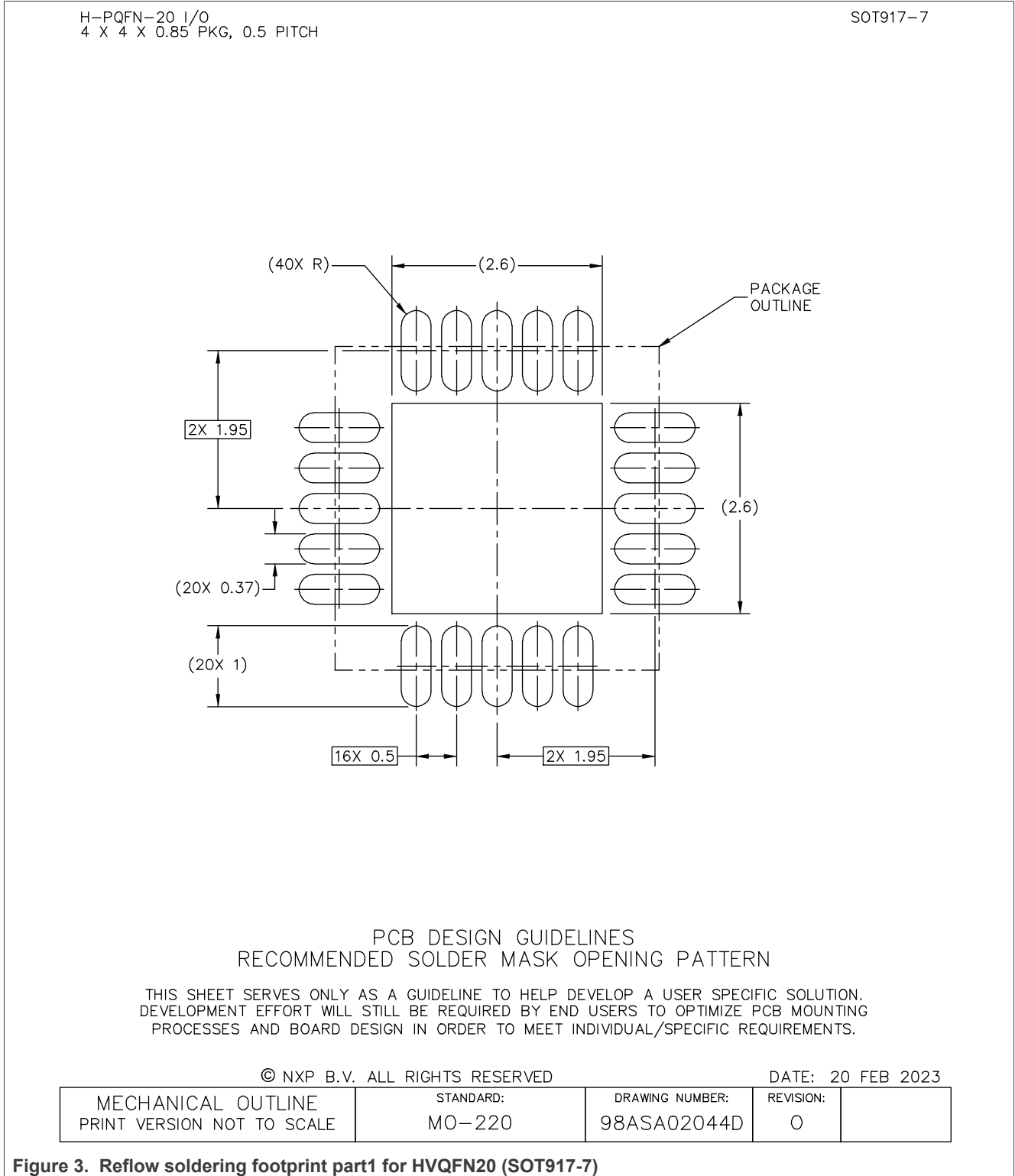
DATE: 20 FEB 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA02044D	REVISION: 0	
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Figure 2. Package outline detail E of HVQFN20 (SOT917-7)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

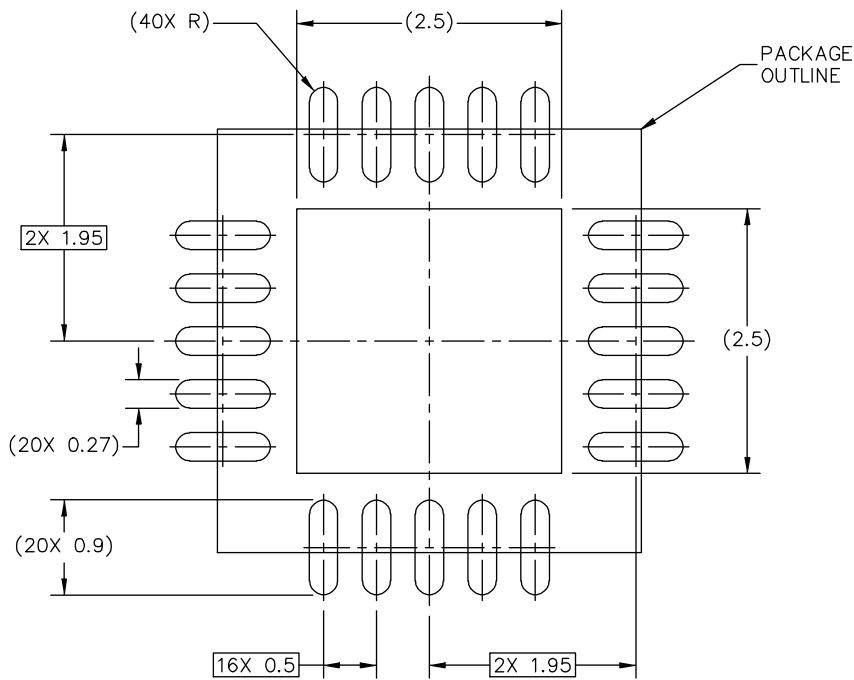
3 Soldering



HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-7



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 20 FEB 2023

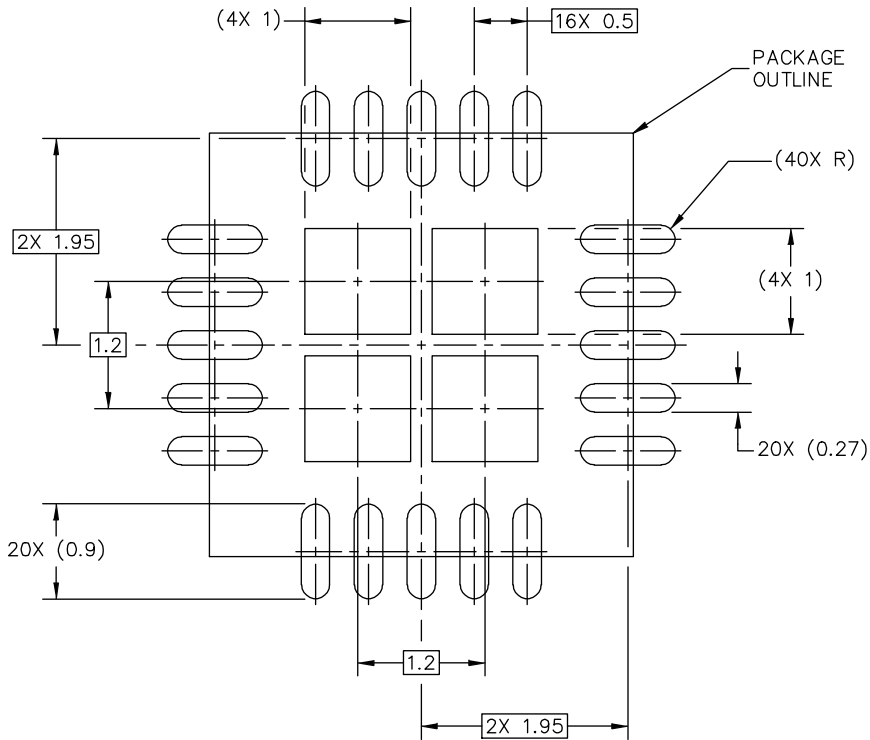
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA02044D	REVISION: 0	
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Figure 4. Reflow soldering footprint part2 for HVQFN20 (SOT917-7)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-7



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.150

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVQFN20 (SOT917-7)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-7

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 6. Package outline note HVQFN20 (SOT917-7)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

4 Legal information

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HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

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